L Number	Hits	Search Text	DB	Time stamp
-	194506	TAB or (tape near3 automate near3 bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:05
-	256146	TAB or (tape near3 automate near3 bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:05
-	256143	TAB or (tape near3 automate near3 bonding) with (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:08
-	282561	TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:14
-	811	(TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) with film near3 carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:27
-	521	(undercoat$3 near2 layer) with (nickel Ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:11
-	5890	intermediate with (palladium Pd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:12
-	1	((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) with film near3 carrier) and ((undercoat$3 near2 layer) with (nickel Ni))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:12
-	4	((undercoat$3 near2 layer) with (nickel Ni)) and (intermediate with (palladium Pd))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:17
-	811	(TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) and ((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) with film near3 carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:15
-	1	((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) and ((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) with film near3 carrier)) and ((undercoat$3 near2 layer) with (nickel Ni))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:15
-	2750	(TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) and layer near3 (nickel Ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:18

-	2079	((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) and layer near3 (nickel Ni)) and (gold Au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:19
-	885	(((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) and layer near3 (nickel Ni)) and (gold Au)) and (palladium Pd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:27
-	395	((((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) and layer near3 (nickel Ni)) and (gold Au)) and (palladium Pd)) and bond$3 adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:28
-	99	(bond$3 adj pad) with (nickel Ni) with (palladium Pd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:31
-	54	(TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) and ((bond$3 adj pad) with (nickel Ni) with (palladium Pd))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 16:51
-	3	((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) and ((bond$3 adj pad) with (nickel Ni) with (palladium Pd))) and film near3 carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:32
-	14494	(copper Cu) with (nickel Ni) with (palladium Pd) with (gold Au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 13:25
-	6680	(copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 13:26
-	21	((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)) with bond$3 near3 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:17
-	12722	(257/81,89,666-677,779-784).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:19
-	138	((257/81,89,666-677,779-784).CCLS.) and ((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:19
-	2	((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)) with film near3 carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:20

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-	17	((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)) with lead near3 frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:38
-	0	(((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)) with lead near3 frame) and wiring near5 pattern$3 and insulat$4 near3 film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:40
-	0	(((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)) with lead near3 frame) and wiring and insulat$4 near3 film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:40
-	1	(((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)) with lead near3 frame) and wiring and insulat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:40
-	1	(((257/81,89,666-677,779-784).CCLS.) and ((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))) and (TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) with film near3 carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:28
-	20	((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)) and (TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) with film near3 carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:43
-	10	(((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)) and (TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near array))) with film near3 carrier) and insulat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:44